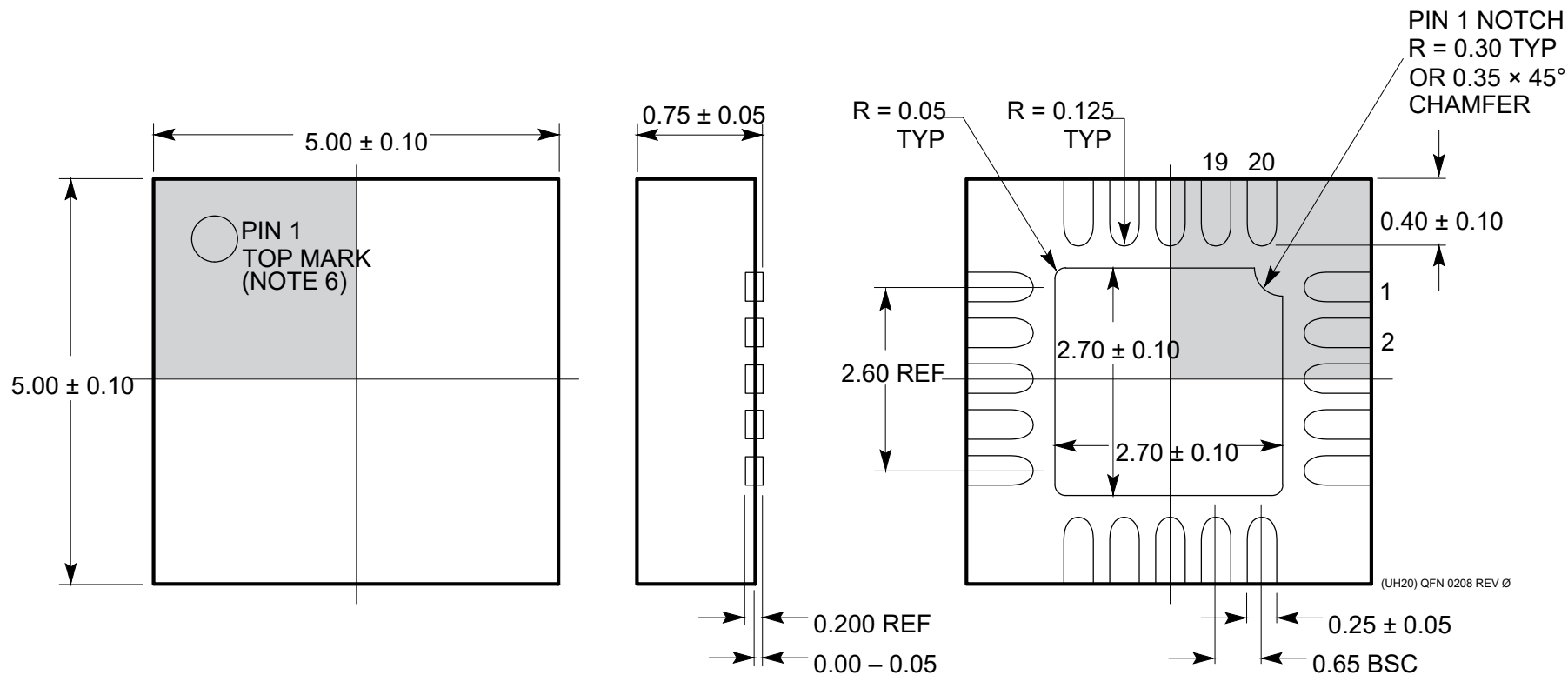


DOCUMENT TYPE: POD
DOCUMENT ID #: 21-100696
REVISION: A-000
DOCUMENT TITLE: PACKAGE OUTLINE, 20L, THIN QFN, 5X5X0.75
EFFECTIVE DATE: 11/29/2022
EXPIRATION DATE:
CHANGE NUMBER: 1175387
ORIGINATOR: Bernard Go

REASON FOR CHANGE:
INITIAL RELEASE
New POD transferring ADI (L-LTC) part into Maxim system.



NOTE:

1. DRAWING IS NOT A JEDEC PACKAGE OUTLINE
2. DRAWING NOT TO SCALE
3. ALL DIMENSIONS ARE IN MILLIMETERS
4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.20mm ON ANY SIDE
5. EXPOSED PAD SHALL BE SOLDER PLATED
6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE
7. REFERENCE DWG # 05-08-1818
8. PACKAGE CODE: T2055+7

BOTTOM VIEW—EXPOSED PAD

—DRAWING NOT TO SCALE—



TITLE:
PACKAGE OUTLINE, 20L, THIN QFN,
5X5X0.75 mm

APPROVAL
IRENE JEONG

DOCUMENT CONTROL NO.
21-100696

REV. A 1/1

